

# Organizational Chart

**North America**

**Japan**

**Europe**

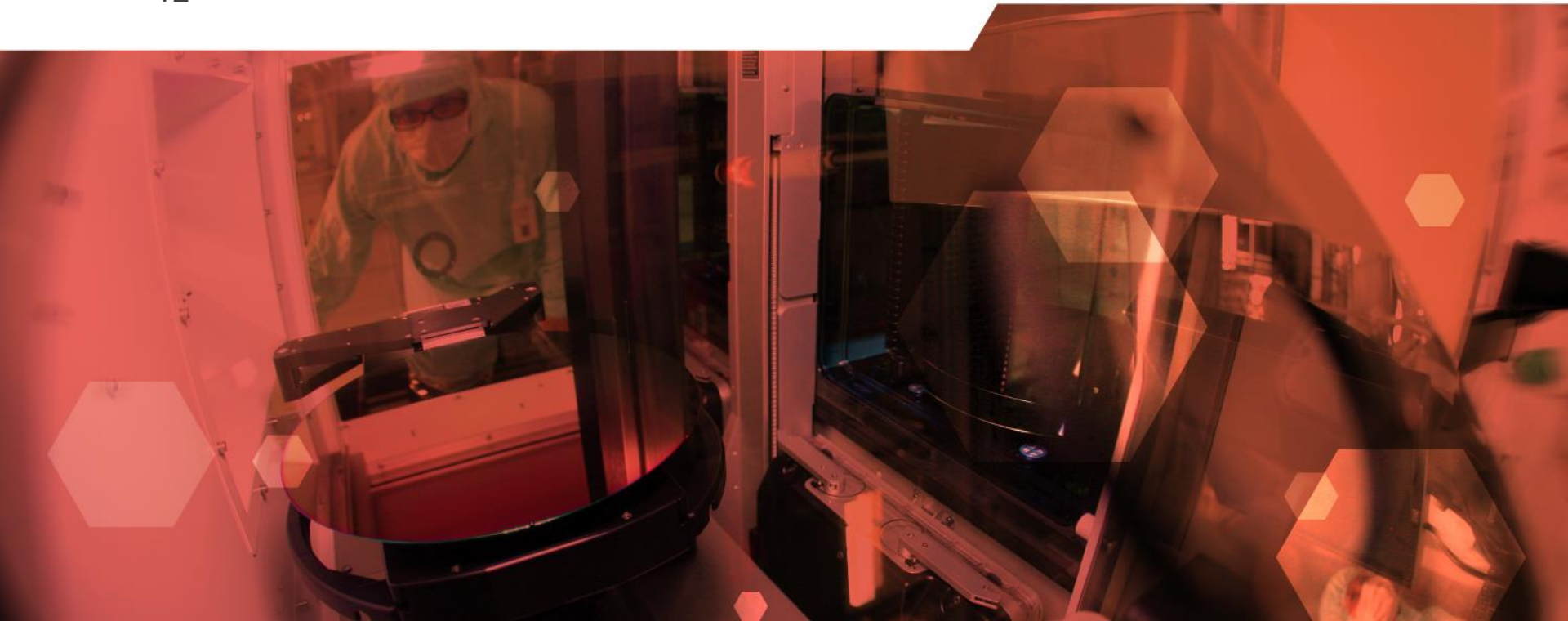
Last Updated: November 2018

v2

**Korea**

**Taiwan**

**China**



# Global Technical Committee (GTC) and Technical Committee (TC) Chapters

Global Technical Committee	Locale						
		China	<u>Europe</u>	<u>Japan</u>	Korea	<u>North America</u>	Taiwan
EH&S				TCC		TCC	TCC
Facilities				TCC	TCC	TCC	
Gases			TCC	TCC		TCC	
Liquid Chemicals			TCC	TCC		TCC	
FPD Materials & Components				TCC	TCC		
FPD Metrology				TCC	TCC		TCC
MEMS/NEMS						TCC	

Legend:

TCC – The Locale has a TC Chapter of the global technical committee.

CFG – The Locale has a TC Chapter Formation Group, as defined in PM 6.5, of the global technical committee.

Note 1: An underlined Locale has an RSC and may also be referred as “a Region” (e.g., “Europe Region”).

Note 2: Some TC Chapters of different global technical committees jointly hold a meeting (indicated in red rectangles).

Global Technical Committee	Locale	China	<u>Europe</u>	<u>Japan</u>	Korea	<u>North America</u>	Taiwan
	Traceability				TCC		TCC
Information & Control			TCC	TCC	TCC	TCC	TCC
Metrics			TCC	TCC		TCC	
Physical Interfaces & Carriers			TCC	TCC		TCC	
Automation Technology			TCC	TCC			TCC
Photovoltaic		TCC		TCC		TCC	TCC
PV Materials		TCC	TCC	TCC		TCC	

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\* In NA, Micropatterning is traditionally called Microlithography

Global Technical Committee	Locale						
		China	<u>Europe</u>	<u>Japan</u>	Korea	<u>North America</u>	Taiwan
Micropatterning (Microlithography*)						TCC	
Silicon Wafer			TCC	TCC		TCC	
Compound Semiconductor Materials			TCC	TCC		TCC	
HB-LED		TCC				TCC	
3D Packaging & Integration**				TCC		TCC	TCC
Automated Test Equipment (ATE)						TCC	

Legend:

TCC – The Locale has a TC Chapter of the global technical committee.

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\* In NA, Micropatterning is traditionally called Microlithography

\*\* 3DS-IC GTC and Assembly & Packaging GTC were integrated into one new GTC as 3D Packaging & Integration GTC in July 2017.

# Regional Standards Committee (RSC) Organizations

# SEMI Europe RSC Organization

Co-Chairs: Bert Planting – ASML, Werner Bergholz – International Standards Consulting

Vice-Chair: Frank Petzold – Trustsec

Europe Chapter of Automation Technology  
Global Technical Committee

C: Christian Hoffmann – PEER Group

Europe Chapter of Liquid Chemicals  
Global Technical Committee

C: Jochen Ruth – Pall Corporation

Europe Chapter of Physical Interfaces & Carriers  
Global Technical Committee

C: Alfred Honold – InReCon

C: Frank Petzold – Trustsec

Europe Chapter of Compound  
Semiconductor Materials  
Global Technical Committee

C: Arnd Weber – SiCrystal

Europe Chapter of Information & Control  
Global Technical Committee

C: Alfred Honold – InReCon

C: Frank Petzold – Trustsec

Europe Chapter of PV Materials  
Global Technical Committee

C: Peter Wagner – Consultant

C: Christian Hagendorf – Fraunhofer CSP

Europe Chapter of Gases  
Global Technical Committee

C: Jochen Ruth – Pall Corporation

Europe Chapter of Metrics  
Global Technical Committee

C: Alfred Honold – InReCon

C: Lothar Pfitzner – FhG IISB

Europe Chapter of Silicon Wafer  
Global Technical Committee

C: Werner Bergholz – International Standards Consulting

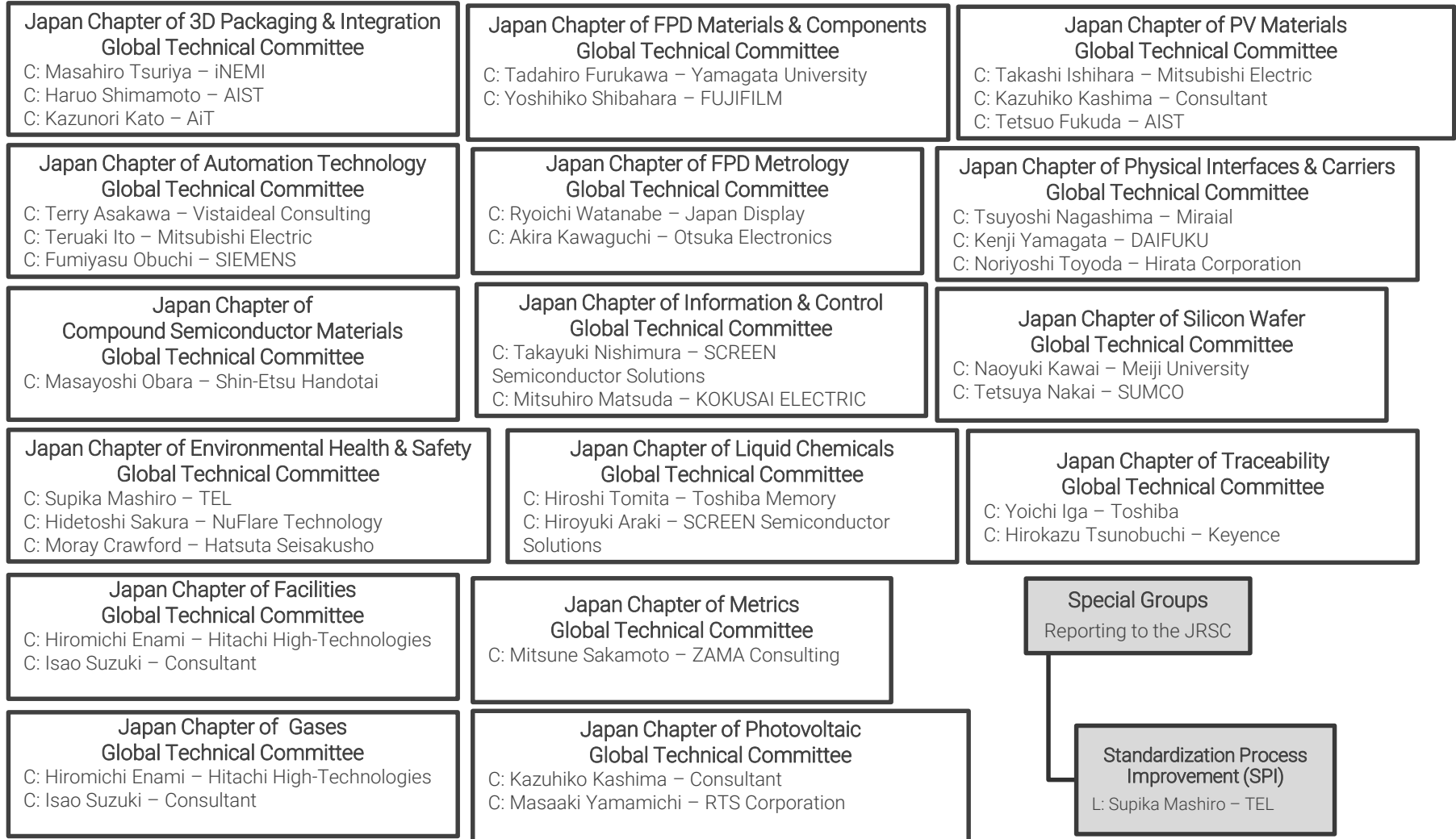
C: Peter Wagner – Consultant

C: Fritz Passek - Siltronic

# SEMI Japan RSC Organization

Co-Chairs: Kenji Yamagata – Daifuku, Hidetoshi Sakura – NuFlare Technology

Vice-Chair: Supika Mashiro – TEL





# SEMI North America (NA) RSC Organization – NA Locale

Co-Chairs: Steve Lewis – BW Design Group, Chris Evanston – Salus Engineering

Vice-Chair: Brian Rubow – Cimatrix



# SEMI North America RSC Organization – China Locale

Co-Chairs: Steve Lewis – BW Design Group, Chris Evanston – Salus Engineering

Vice-Chair: Brian Rubow – Cimatrix

**China Chapter of Photovoltaic  
Global Technical Committee**

C: Guangchun Zhang – CanadianSolar

C: Jun Liu – China Electronics Standardization Institute

**China Chapter of PV Materials  
Global Technical Committee**

C: Guangchun Zhang – CanadianSolar

C: Jun Liu – China Electronics Standardization Institute

**China Chapter of HB-LED  
Global Technical Committee**

C: Hongbo Zuo – AURORA

C: Jiangbo Wang – HC SemiTek

# SEMI North America RSC Organization – Korea Locale

Co-Chairs: Steve Lewis – BW Design Group, Chris Evanston – Salus Engineering

Vice-Chair: Brian Rubow – Cimatrix



# SEMI North America RSC Organization – Taiwan Locale

Co-Chairs: Steve Lewis – BW Design Group, Chris Evanston – Salus Engineering

Vice-Chair: Brian Rubow – Cimatrix

## Taiwan Chapter of 3D Packaging & Integration Global Technical Committee

C: Wendy Chen – King Yuan Electronics

C: Chien-Chung Lin – ITRI

C: Roger Hwang – ASE

## Taiwan Chapter of Flat Panel Display Global Technical Committee

C: Mike Yao – CMS/ITRI

C: Jia-Ming Liu – TDMDA

## Taiwan Chapter of Automation Technology Global Technical Committee

C: K.C. Chou – ASE

C: Jen-Hui Tsai – ITRI

C: Gwo-Sheng Peng – ITRI/CMS

C: Yung-Mao Zheng – MIRDC

## Taiwan Chapter of Information & Control Global Technical Committee

C: Robert Chien – TSMC

## Taiwan Chapter of Environmental Health & Safety Global Technical Committee

C: Shuh-Woei Yu – SAHTECH

C: Fang-Ming Hsu – TSMC

## Taiwan Chapter of Photovoltaic Global Technical Committee

C: T.C. Wu – CMS/ITRI

C: J.S. Chen – TeraSolar

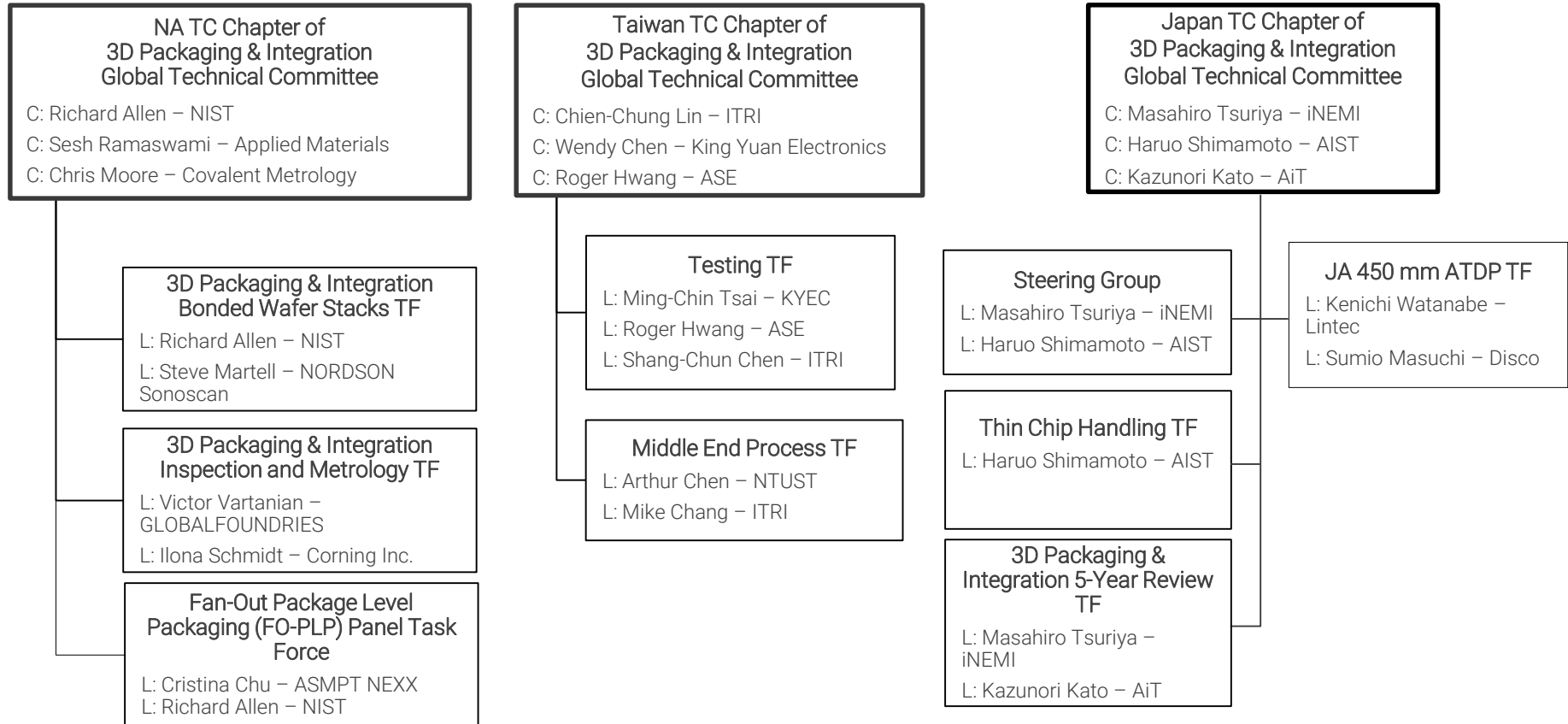
C: Ray Sung – UL Taiwan

## ISC Taiwan Advisor

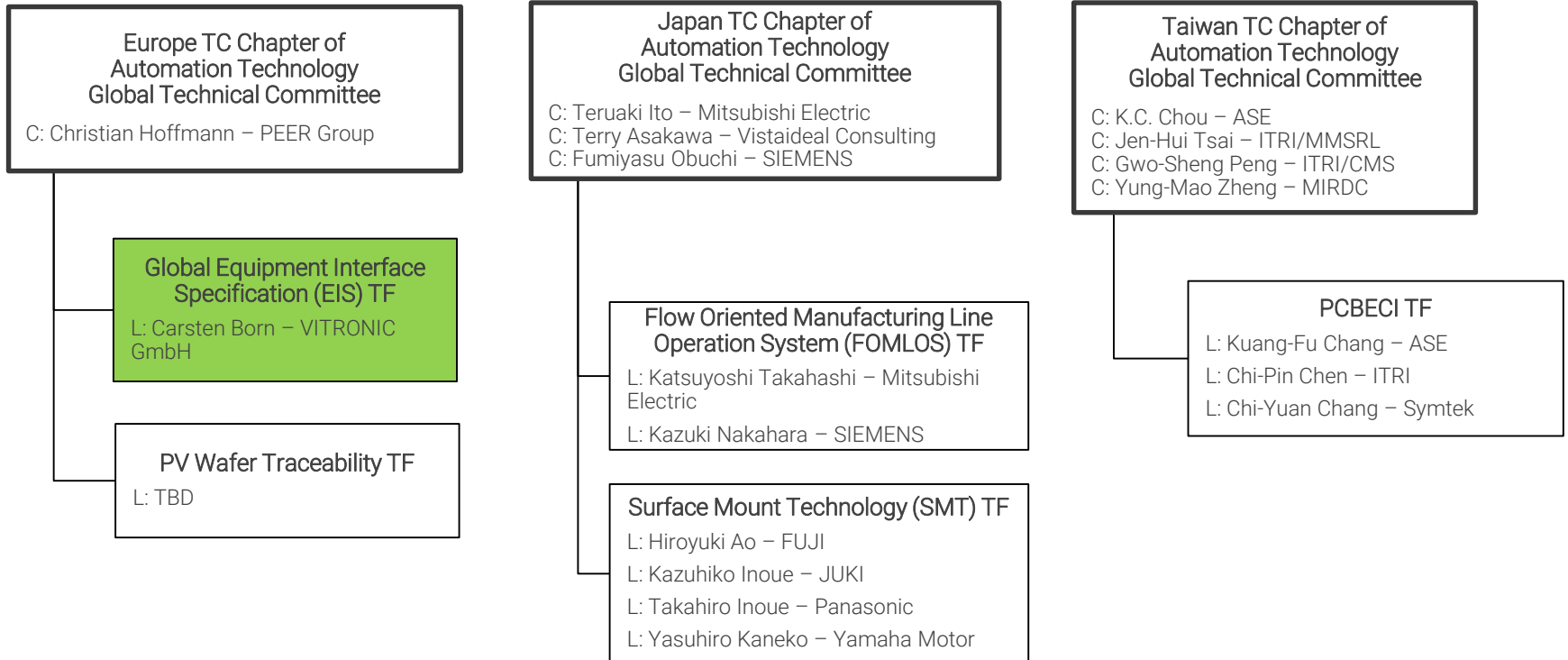
Tzeng-Yow Lin – CMS/ITRI


# Organization of Each TC Chapter

# 3D Packaging & Integration (3DP&I) Global Technical Committee

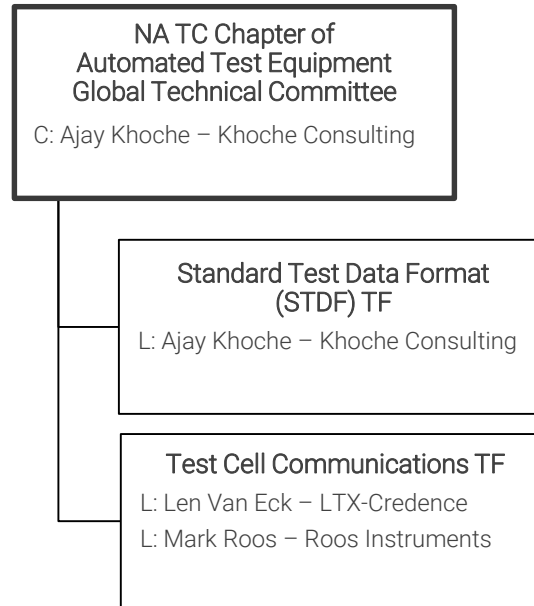


# Automation Technology (AT) Global Technical Committee



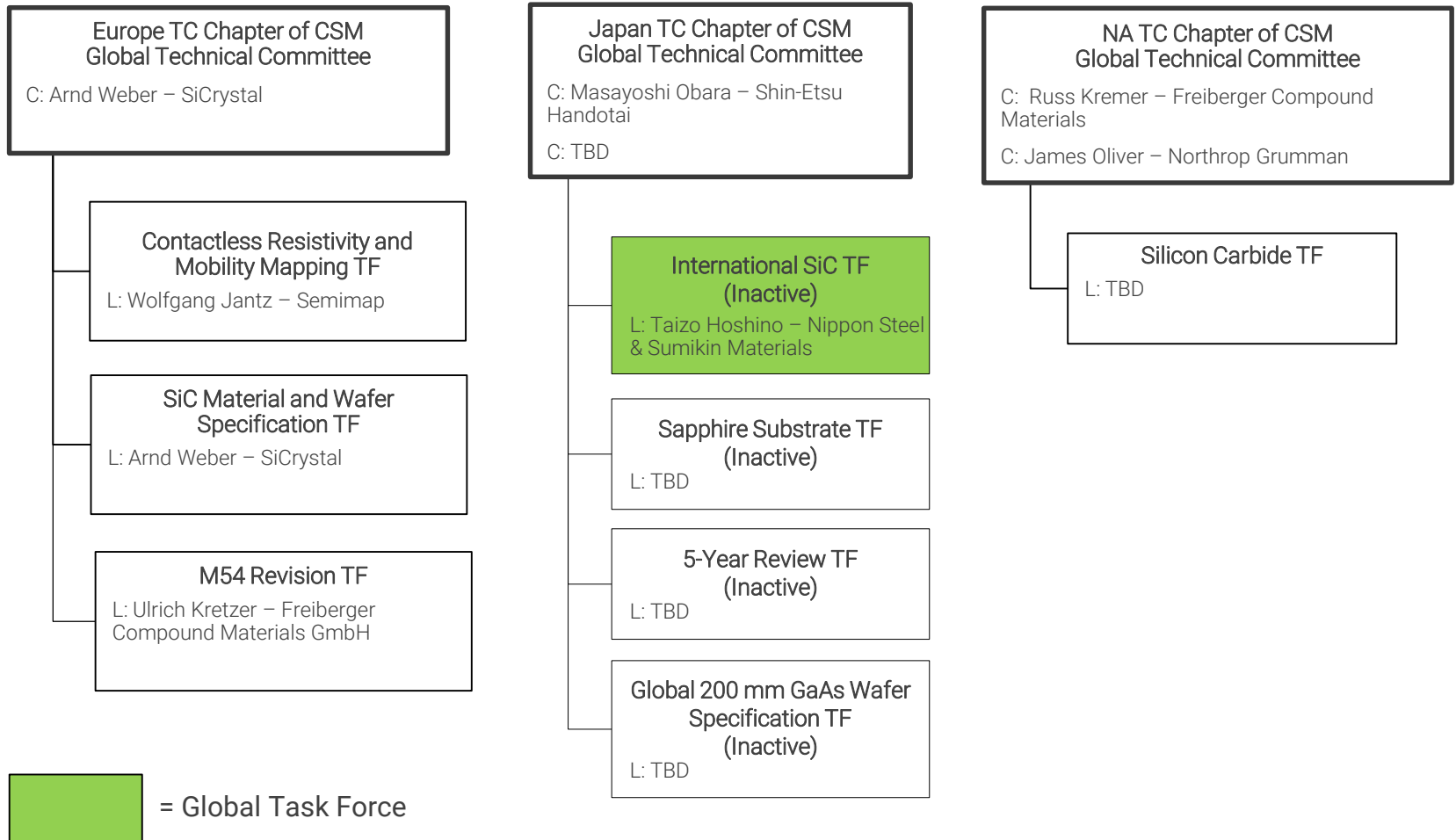
 = Global Task Force

# Automated Test Equipment (ATE) Global Technical Committee

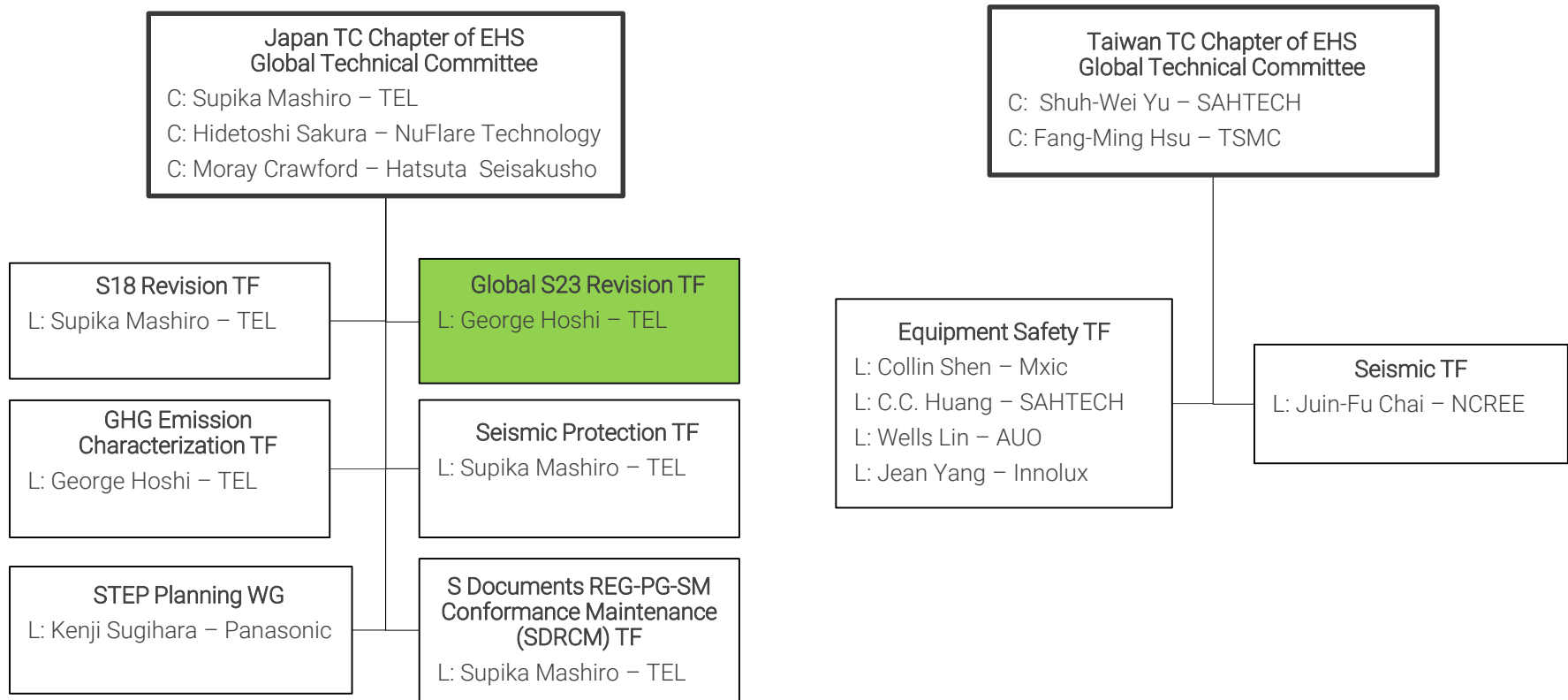





# Compound Semiconductor Materials (CSM) Global Technical Committee

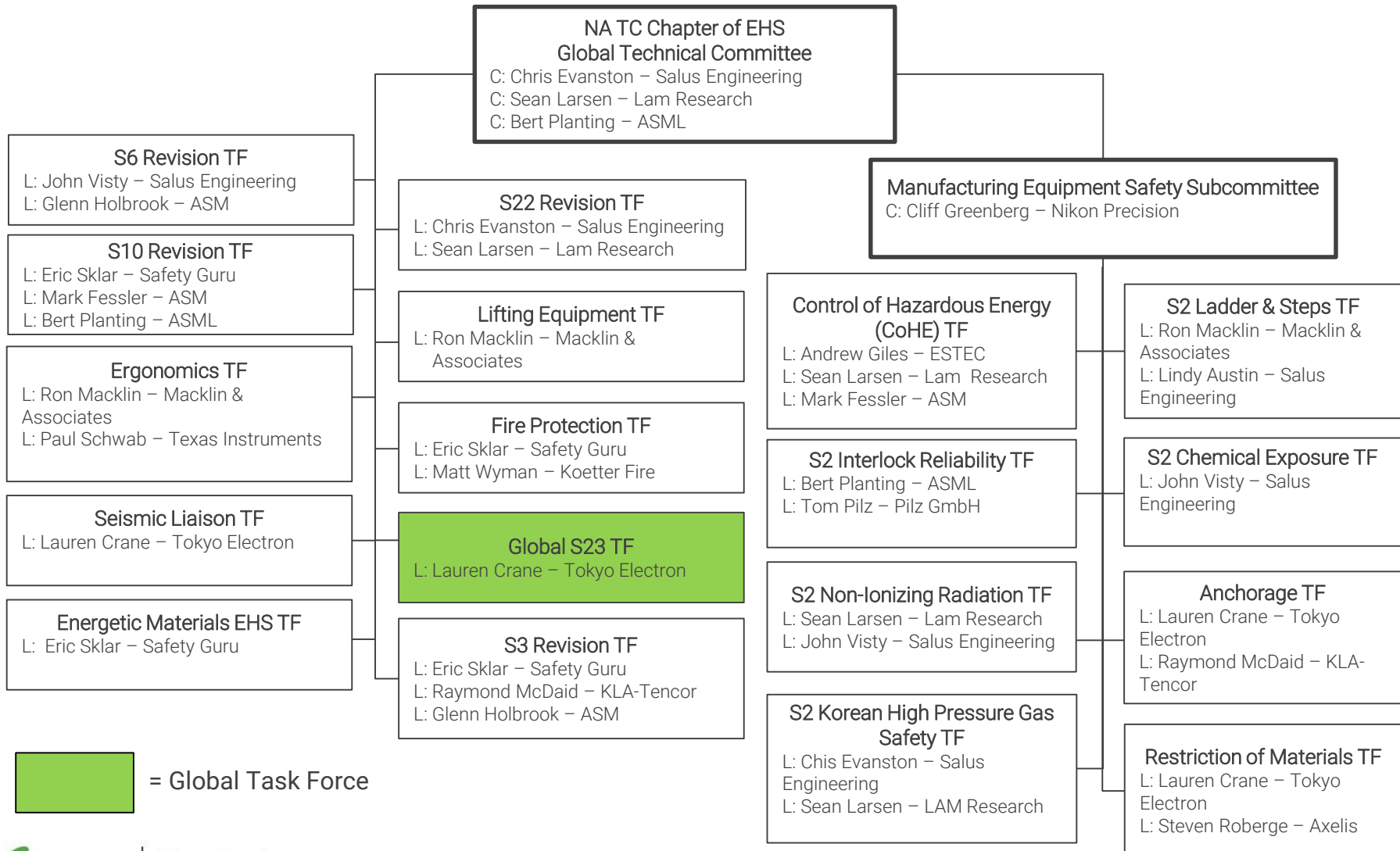


# Environmental, Health & Safety (EH&S) Global Technical Committee



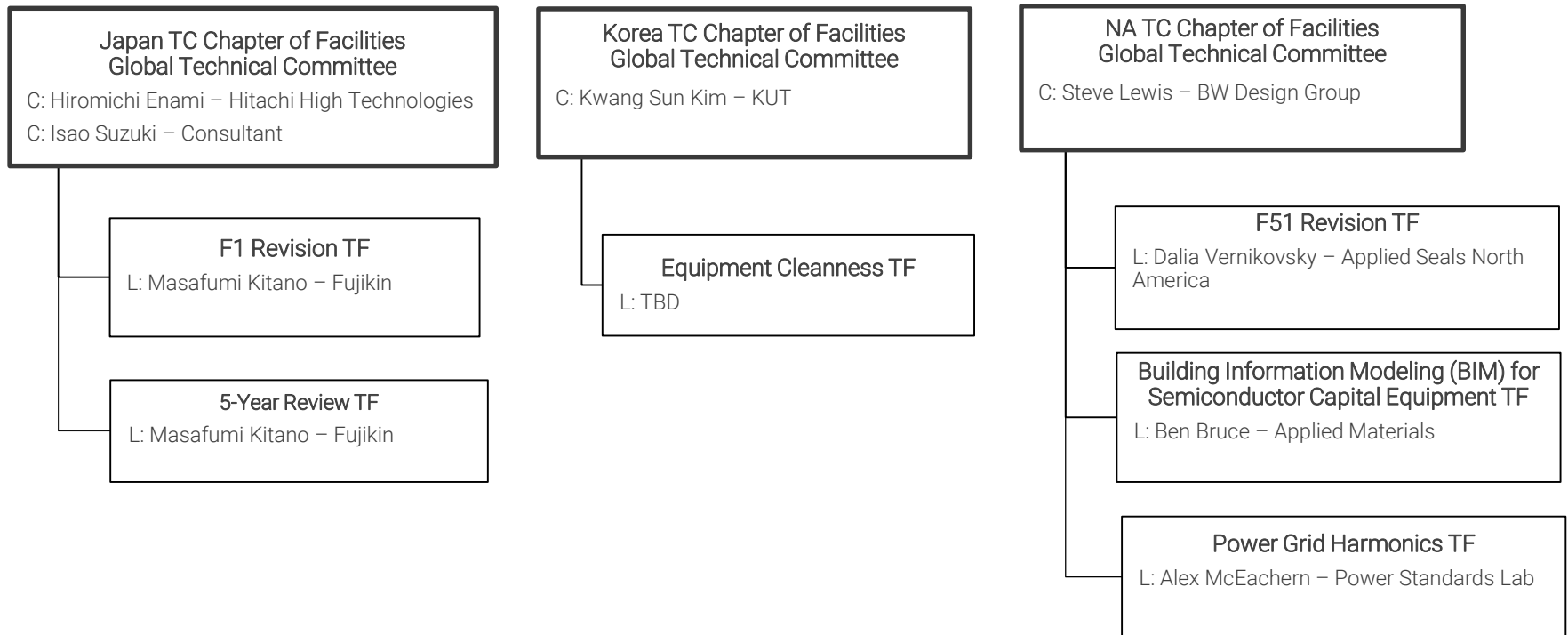
 = Global Task Force

# Environmental, Health & Safety (EH&S) Global Technical Committee

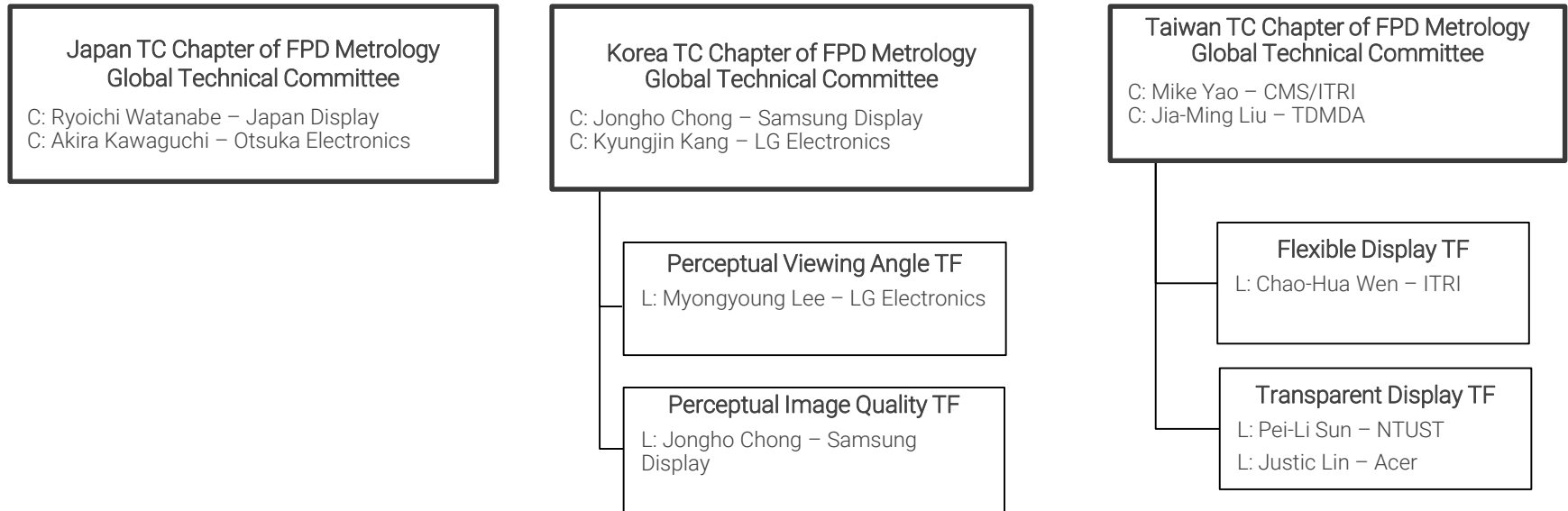


# Facilities

## Global Technical Committee



# FPD Metrology Global Technical Committee



# FPD Materials & Components Global Technical Committee

**Japan TC Chapter of FPD Materials & Components  
Global Technical Committee**  
C: Tadahiro Furukawa – Yamagata University  
C: Yoshihiko Shibahara – Fujifilm

**Flexible Display TF**  
L: Haruhiko Itoh – Teijin  
L: Tadahiro Furukawa – Yamagata University

**FPD Mask TF**  
L: Kazuya Shiojiri – SK Electronics  
L: Hirofumi Ihara – HOYA

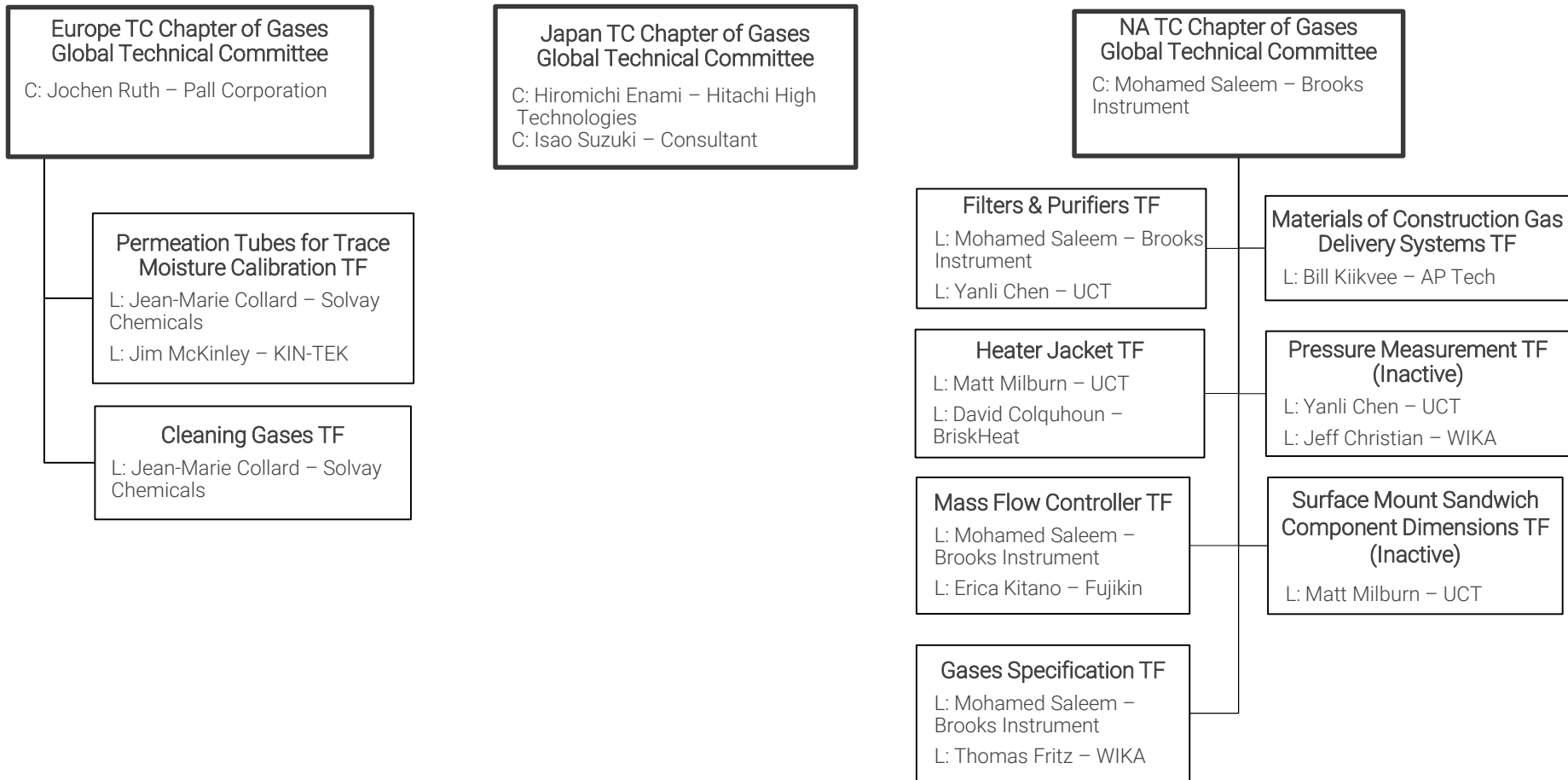
**FPD Color Filter TF**  
L: Tadahiro Furukawa – Yamagata University

**Polarizing Film TF**  
L: Yoshihiko Shibahara – Fujifilm  
L: Motoshige Tatsumi – Nitto Denko

**Korea TC Chapter of FPD Materials & Components  
Global Technical Committee**  
C: Jongseo Lee – Dell  
C: Il-Ho (William) Kim – Light Measurement Solution

# Gases

## Global Technical Committee



# HB-LED

## Global Technical Committee

**China TC Chapter of HB-LED  
Global Technical Committee**  
C: Hongbo Zuo – AURORA  
C: Jiangbo Wang – HC SemiTek

**Single Crystal Sapphire TF**  
L: Yong Ji – Guizhou Haotian Optoelectronics Technology  
L: Xinhong Yang – AURORA

**Sapphire Single Crystal Ingot TF**  
L: Hongbo Zuo – AURORA

**GaN based LED Epitaxial Wafer TF**  
L: Jiangbo Wang – HC SemiTek

**Sapphire Single Crystal Orientation TF (Inactive)**  
L: Songbin Zhao – DDXDF

**Patterned Sapphire Substrate TF**  
L: Jianzhe Liu – ECBO

**HB-LED Equipment Communication Interface TF**  
L: Steven Lee – AMEC  
L: Edward Lee – AMEC

**NA TC Chapter of HB-LED  
Global Technical Committee**  
C: Mike Feng – Silian  
C: Chris Moore – Covalent Metrology  
C: Andrew Kim – InnovationforX

**Patterned Sapphire Substrate (PSS) TF**  
L: Win Baylies – BayTech-Resor

**HB-LED Equipment Communication Interfaces TF (Inactive)**  
L: Brian Rubow – Cimatrix

**HB-LED Equipment Automation Interfaces TF (Inactive)**  
L: Daniel Babbs – Brooks Automation  
L: Jeff Felipe – Entegris

**Test Methods TF (Inactive)**  
L: Peter Wagner – Self

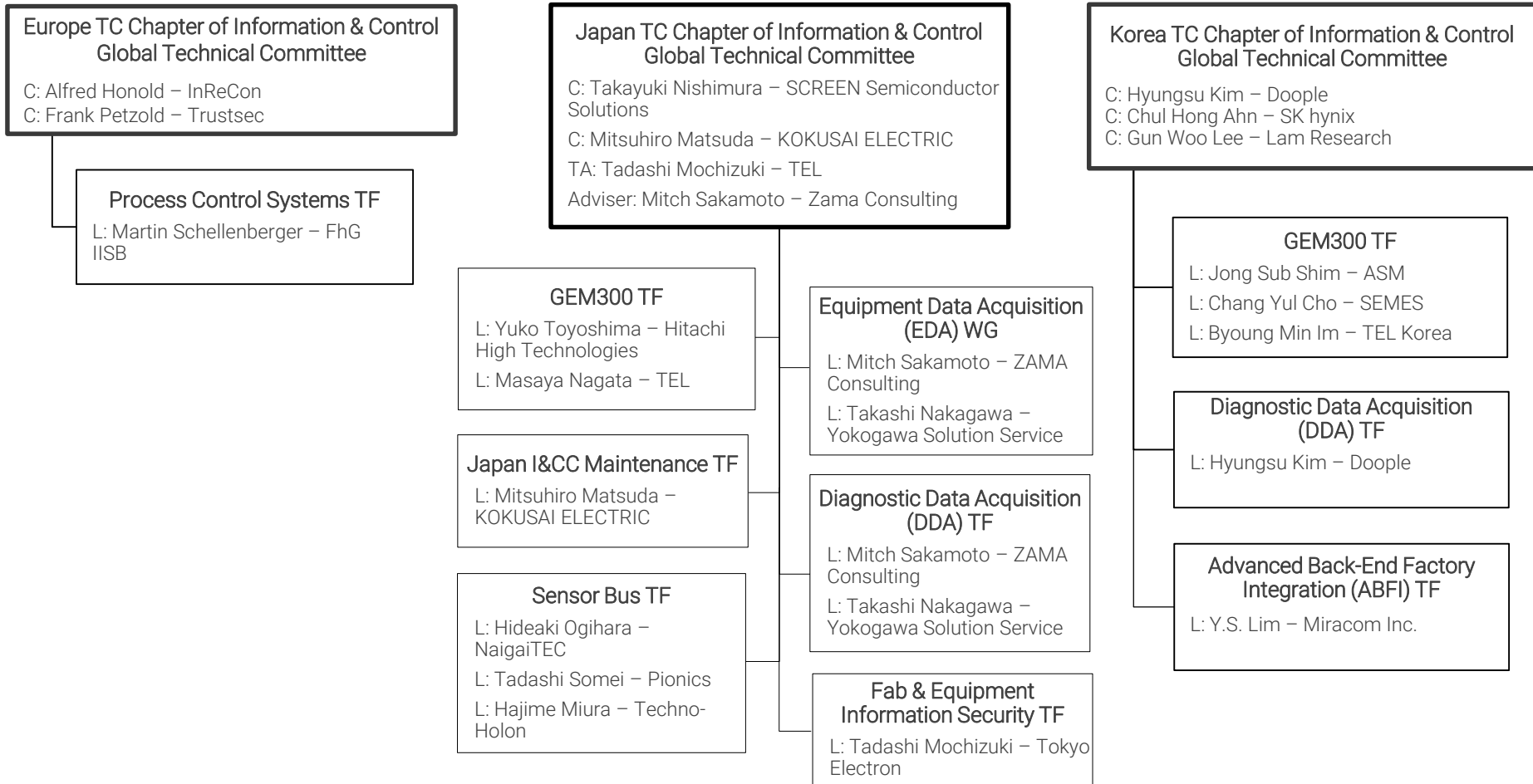
**HB-LED Wafer TF**  
L: Win Baylies – BayTech-Resor

**HB-LED Impurities & Defects in Sapphire Wafers TF (Inactive)**  
L: Luke Glinski – GT Advanced Technologies

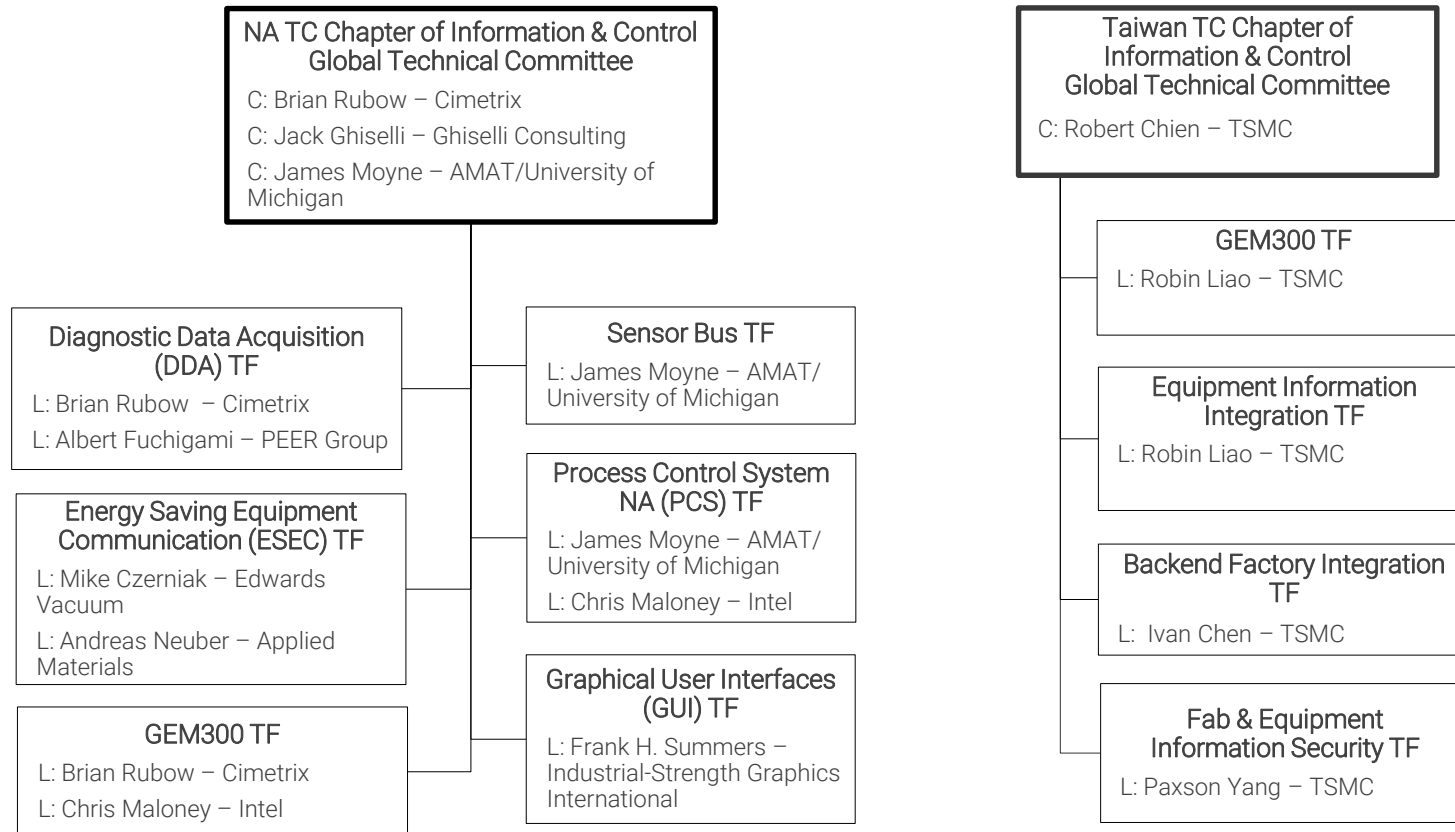
**HB-LED Source Materials TF (Korea)**  
L: Paul Ahn – Veeco  
L: H.B. Joo – Aixtron  
L: Sungjin Jun – LG Innotek  
L: Deok-gil – Samsung Electronics



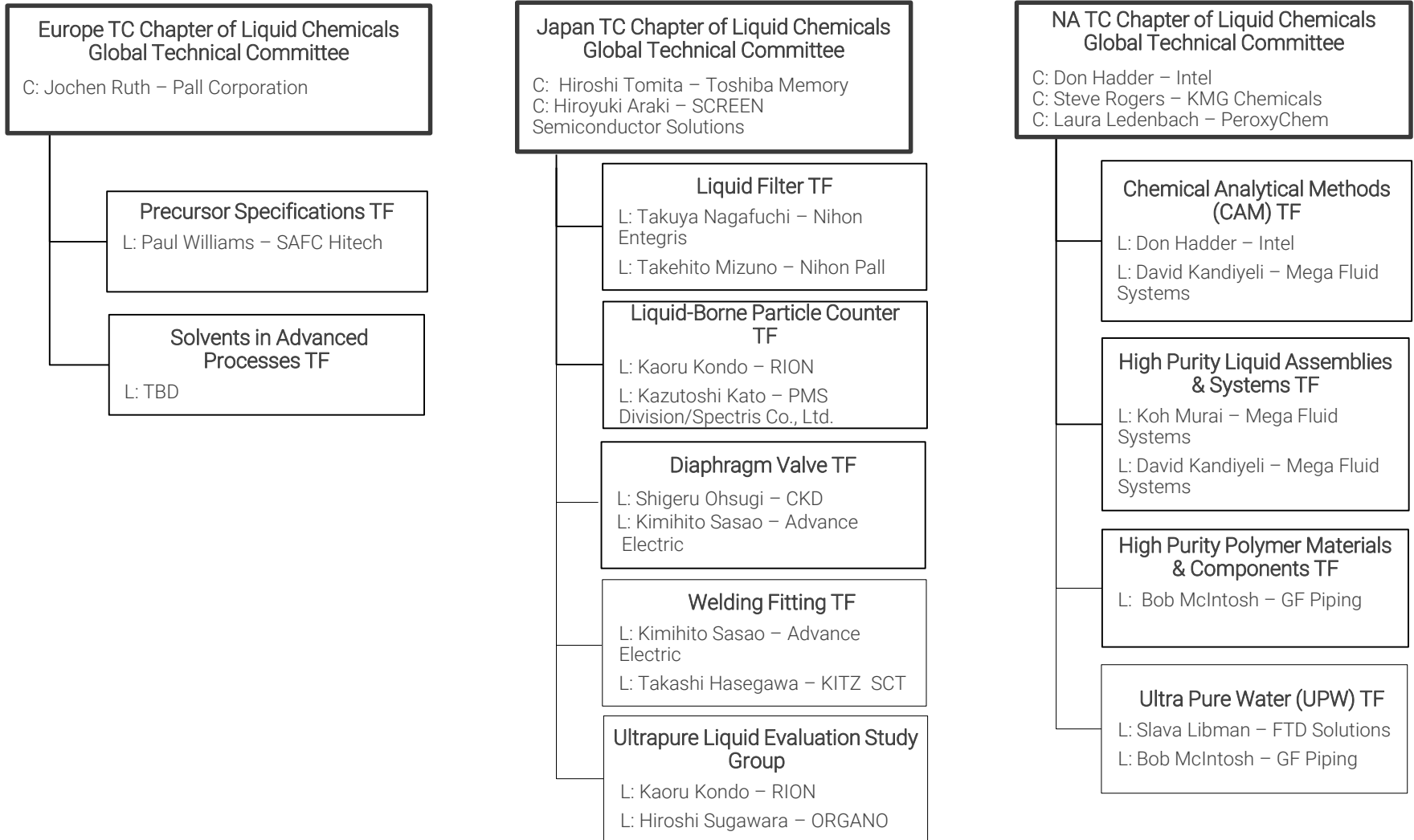
# Information & Control (I&C) Global Technical Committee



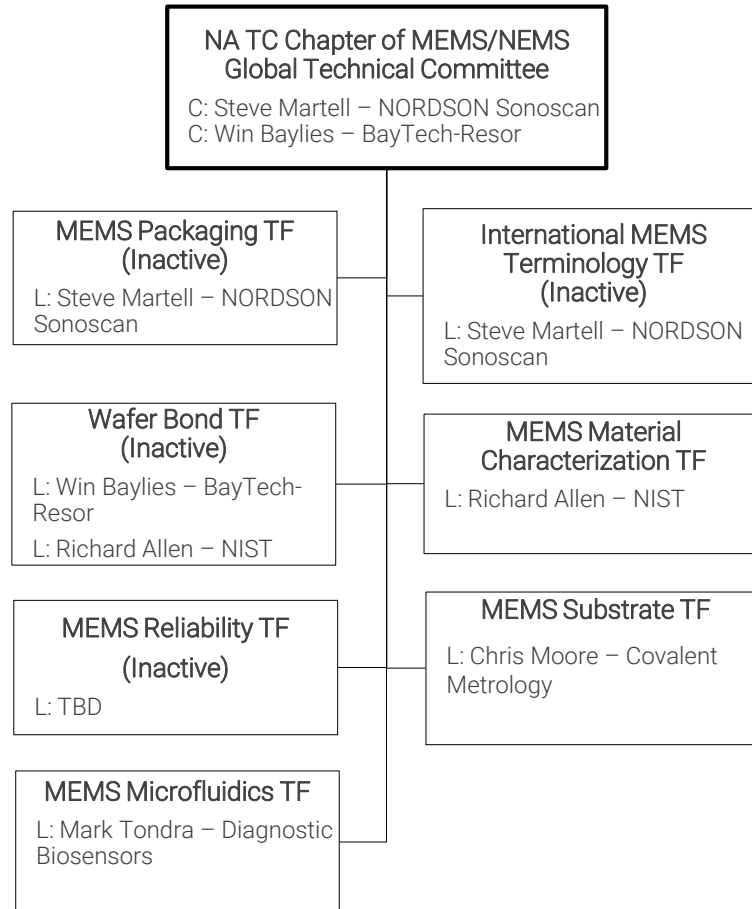
# Information & Control (I&C) Global Technical Committee



# Liquid Chemicals Global Technical Committee

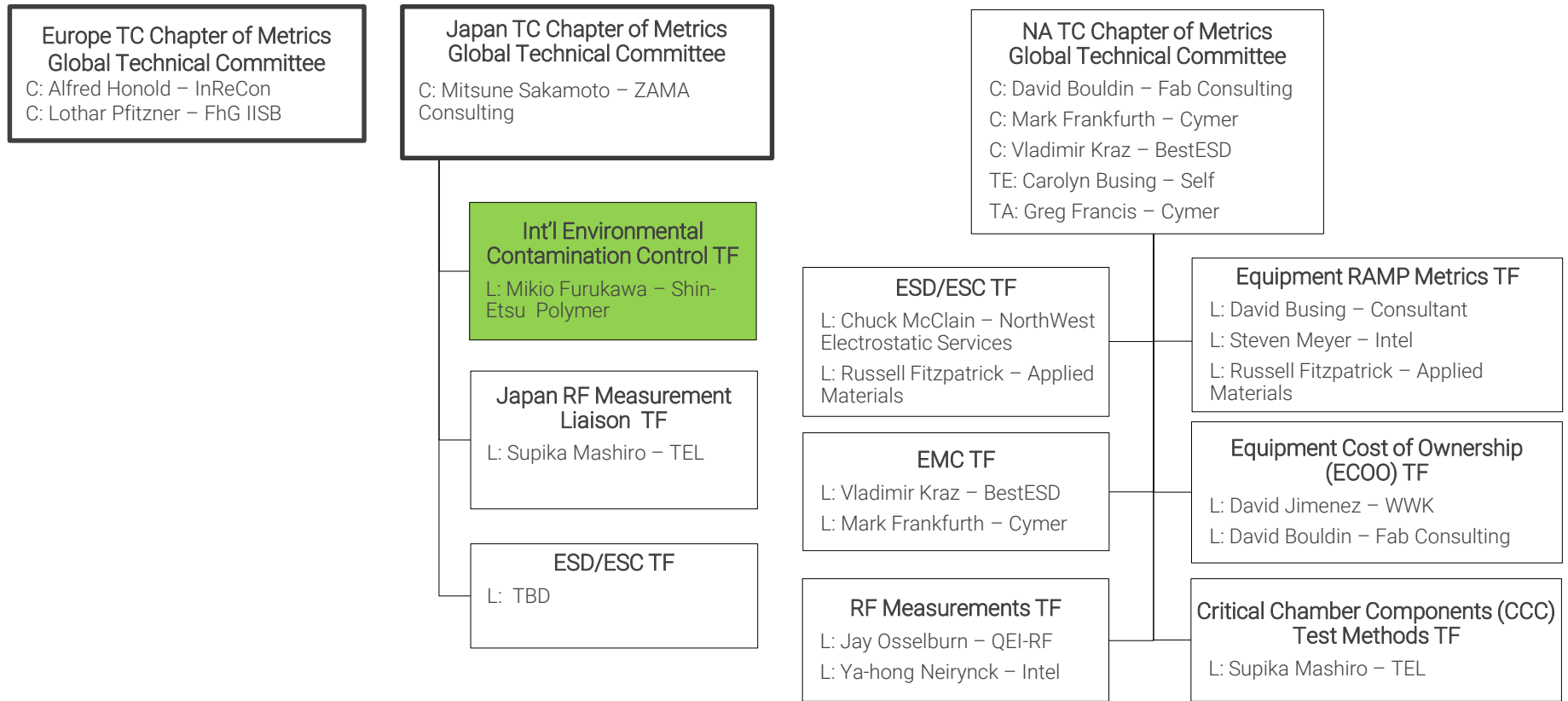



# MEMS/NEMS Global Technical Committee



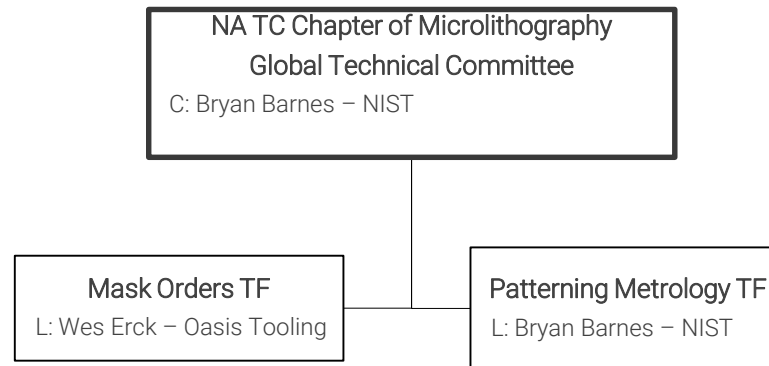
# Metrics

## Global Technical Committee

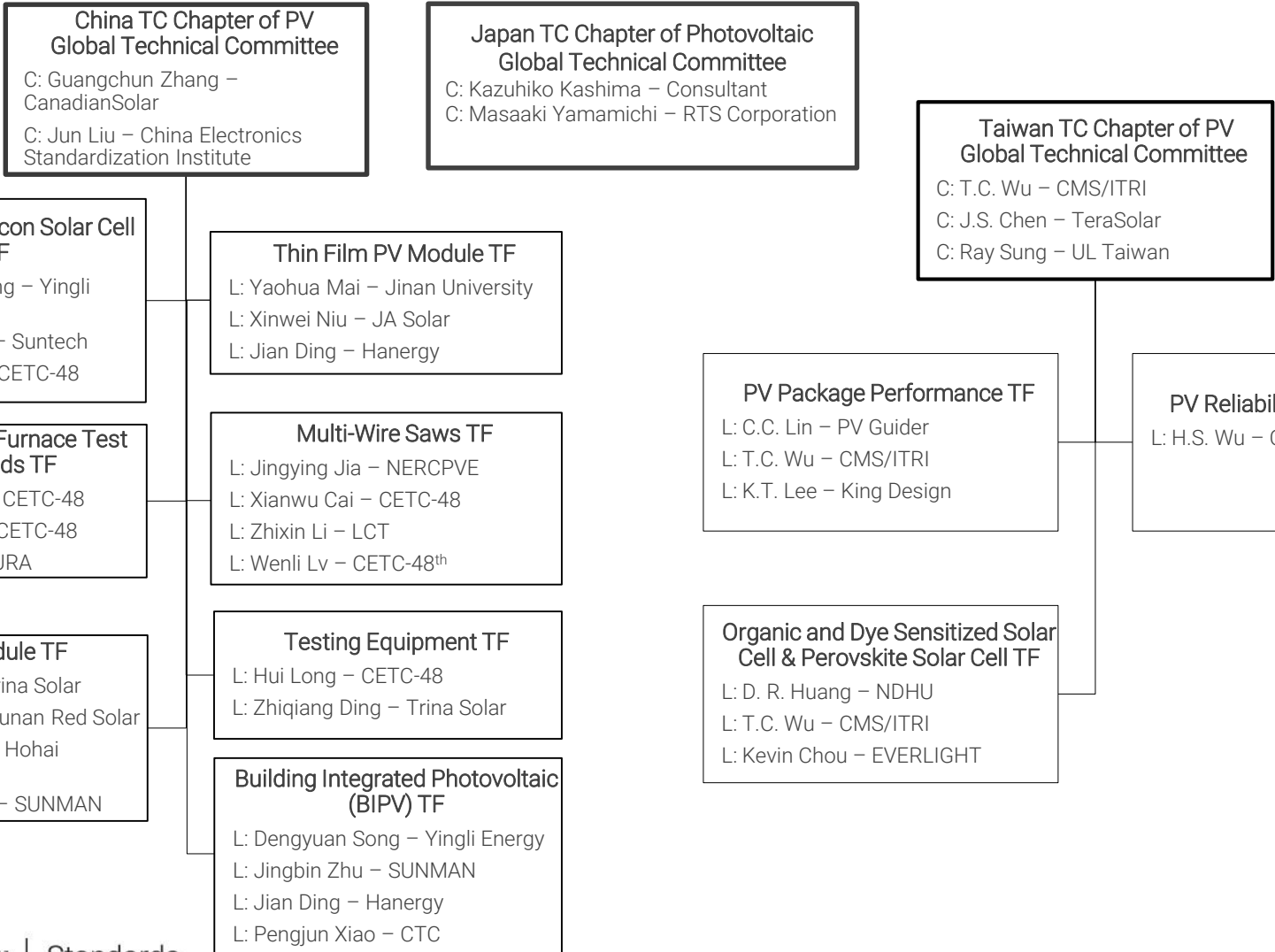


 = Global Task Force

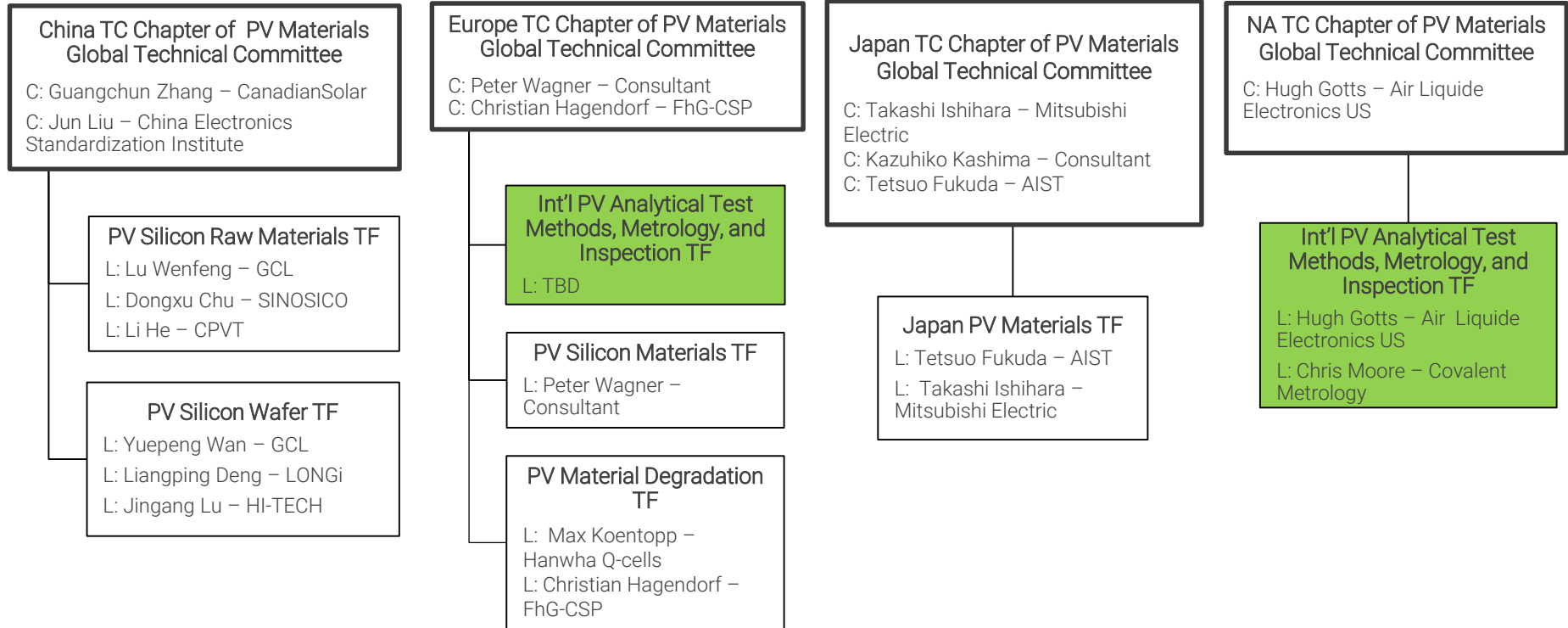
# Micropatterning Global Technical Committee




# Photovoltaic (PV) Global Technical Committee



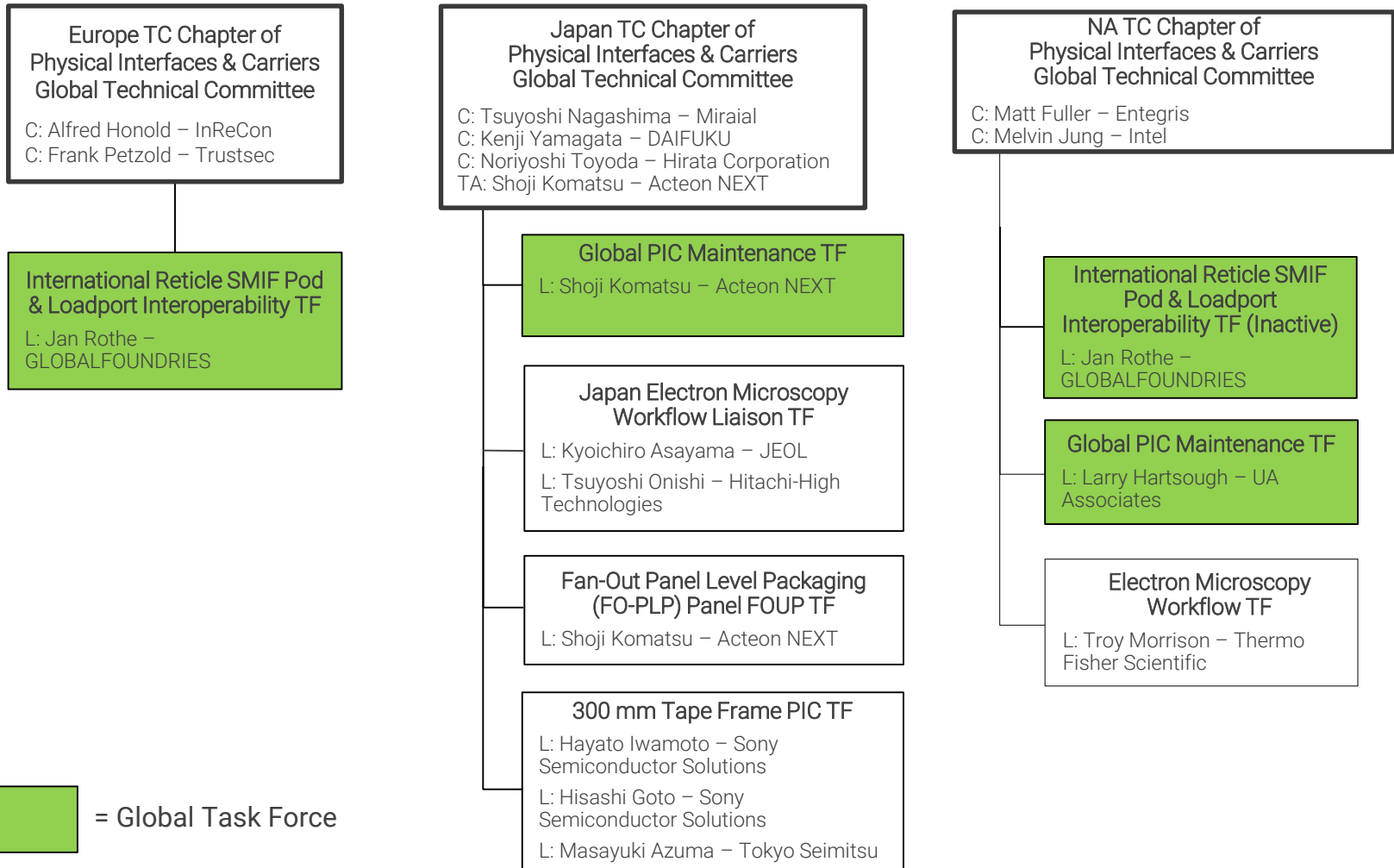
# PV Materials Global Technical Committee



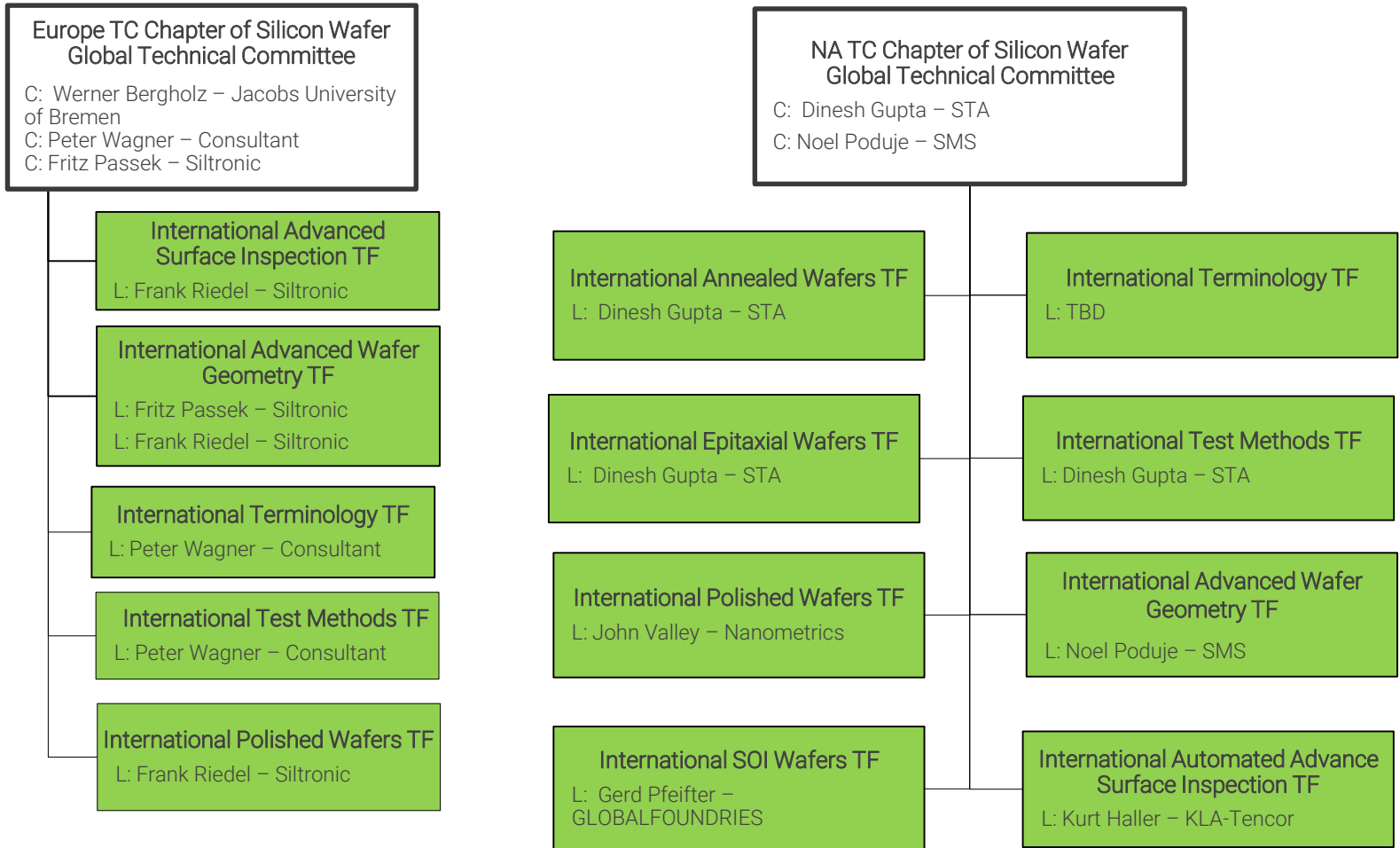
 = Global Task Force




# Physical Interfaces & Carriers (PIC) Global Technical Committee

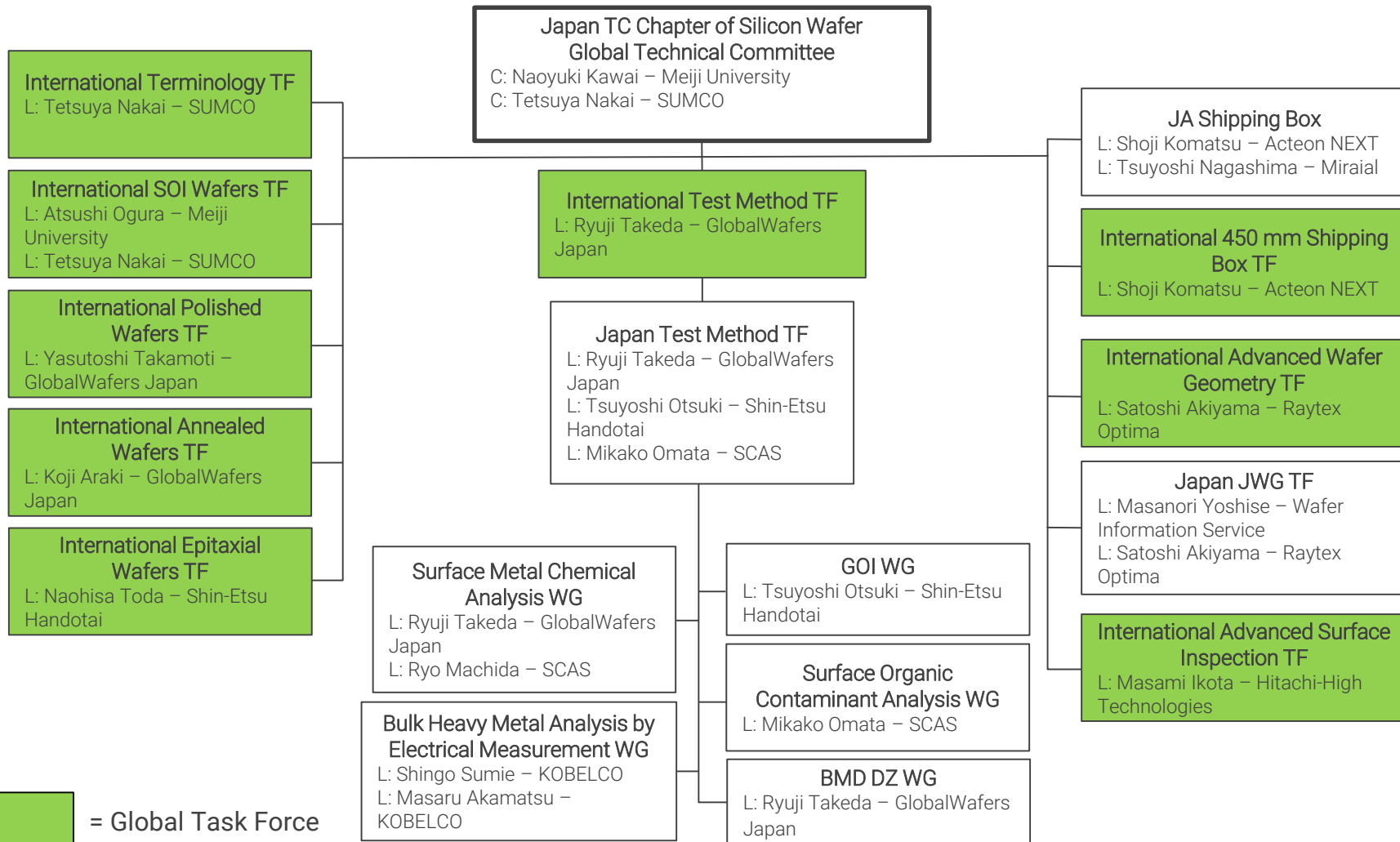


# Silicon Wafer Global Technical Committee



 = Global Task Force

# Silicon Wafer Global Technical Committee



# Traceability Global Technical Committee

